



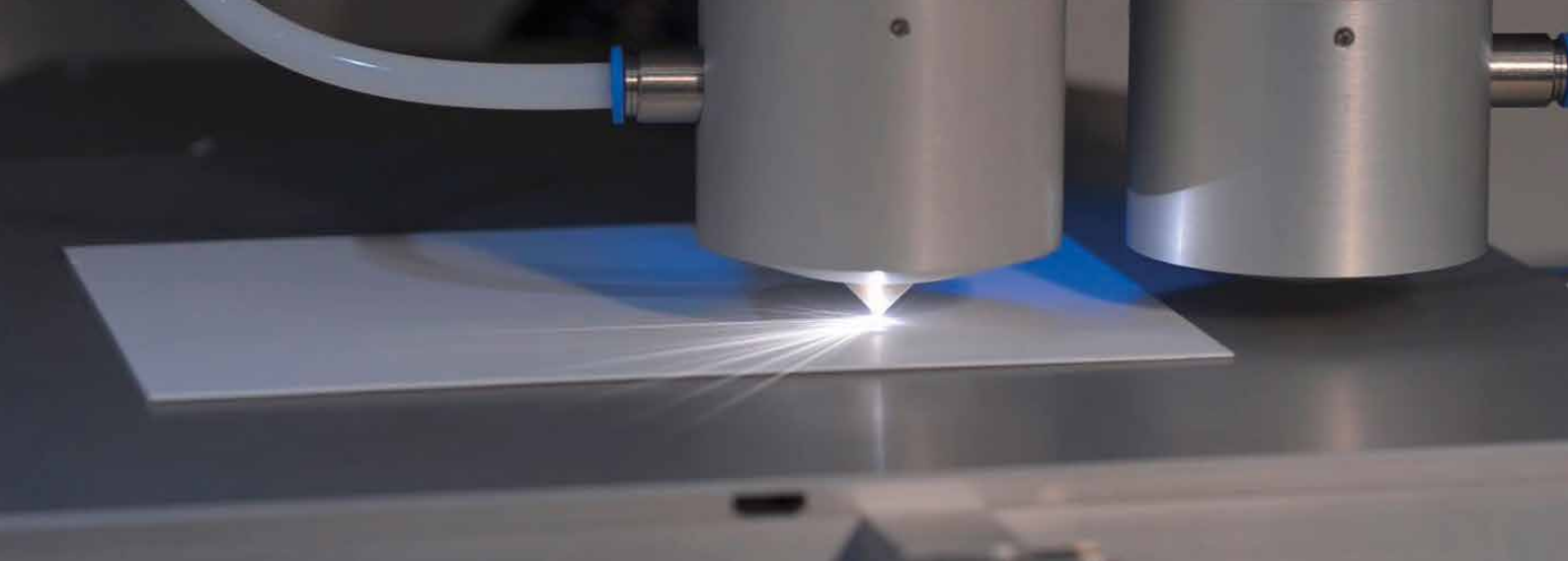
INNOLAS
solutions

INNOVATION FOR THE
NEXT GENERATION



ILS-LT LINEAR TABLE MACHINE

VERSATILE **LASER SYSTEM**
FOR MICRO MATERIAL PROCESSING

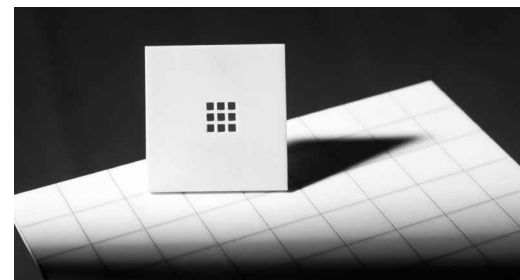
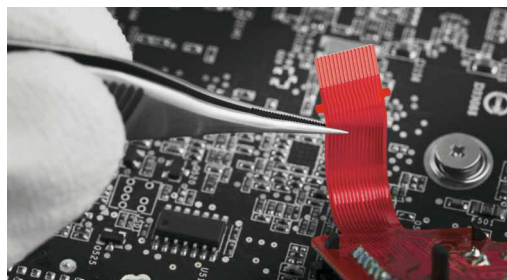


FEATURES

- ◆ Fixed optic or scanner setup
- ◆ Single or dual process heads
- ◆ Process gas (N₂, O₂, Ar, ...)
- ◆ Processing one or more substrates in parallel
- ◆ Automatic camera calibration
- ◆ Automated routines for reference runs
- ◆ Automated process control
- ◆ Automated vision system for precision alignment and scaling, offset, trapezoidal and rotation compensation
- ◆ Stand alone and production line integrated system

OPTIONS

- ◆ Import of CAD files (e.g. DXF, DWG) and Excellon 2, Sieb & Meyer and Gerber file formats
- ◆ SQL data base for process and event tracking
- ◆ MES interface (SECS GEM PV2)
- ◆ Integrated process metrology
- ◆ Semi-automatic handling (R&D)
- ◆ Fully-automatic handling (production)



APPLICATIONS

Micro Via Drilling, Routing, Depaneling, Micro Structuring, Selective Ablation, Cavity Formation

ACCURACY

< +/-10 µm abs.
< +/-2 µm repeatability

SUBSTRATE

Dimension up to 610 x 410 mm
Thickness > 50 µm
PCB, ceramic, silicon, metal

AVAILABLE LASER SOURCES

Wave length: 9.4, 10.6 µm (CO₂), 1064, 1030, 532, 515, 355 nm
Pulse: µs, ns, ps, fs

DIMENSIONS

1700 x 2100 x 2700 mm

